

$\begin{array}{c} {\rm Electronic\ systems\ engineering} \\ {\bf PARticulate\ MAtter\ monitoring\ system} \\ {\rm Technical\ report} \end{array}$

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0 Project specifications

The PAR.MA. (PARticulate MAtter monitoing system) is a smart particulate matter sensor to measure the concentration of PM2.5 in the environment where it is placed and to report the measurement thanks to the bluetooth technology.

The main specifications of the system are

• PM2.5 accuracy: 10 ug/m3

• Operating temperature : -10 C to 50 C

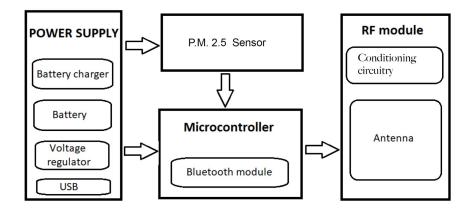
• Portable form factor

• Rechargeable battery

The main application for this system is to measure the PM2.5 concentration of an open air environment (e.g. main street of a city center), however it can be used inside a home as well. The system is made up of four main blocks, namely

- Power supply: this block is dedicated to the power distribution of the system and the recharge process
- Microprocessor: this block is dedicated to the computational unit of the system; it reads the data coming from the sensor and start the bluetooth communication
- PM2.5 sensor: this block is dedicated to the sensing of the PM2.5 concentration; the communication with the microprocessor is achieved thanks to the UART protocol
- RF module: this block is dedicated to control the PCB antenna

The entire block diagram is shown in the following figure.



1 Design flow

The design and development of the project followed the step in the table below.

	I week	II week	III week	IV week	V week	VI week	VII week
Specification							
Component							
Schematic							
PCB & Gerber							
Report							

The following steps were followed in order to complete the system design

• At first the system specifications were defined, the choices in this stage influenced the whole design and the following steps.

- Then the components for the design were chosen according to the initial specifications.
- The schematics were created on ORCAD Capture connecting the components selected in the previous step.
- The PCB was designed according to the manufacturer constraints, the final gerber files were sent to the manufacturer for further checks.
- The technical report was written in order to explain the choices for the system design.

2 Component selection

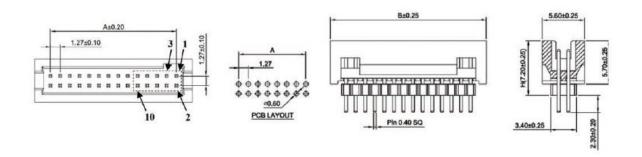
In the following section the component selection process will be broken down, showing the specifications of the component selected for the final design and the reason behind the choice.

2.1 PM2.5 sensor



The Telaire SM-UART-04L sensor is a PM2.5 sensor with a digital interface for input commands/output readings. The digital interface allows a simple interface with the microprocessor, no conditioning circuitry is needed. The main specifications and features are reported below (directly taken from the datasheet).

Pin#	Pin Name	Description
1	5V	Input Supply Voltage
2	5V	Input Supply Voltage
3	GND	Ground
4	GND	Ground
5	RESET	Reset Pin @3.3V TTL, Low level reset
6	NC	8 <u>-</u> 2
7	RXD	UART Receiver @ 3.3V TTL
8	NC	1-1
9	TXD	UART Transceiver @ 3.3V TTL
10	SET/SLEEP	Working Mode Pin @ 3.3V TTL Floating or high level for normal working condition Low level for dormancy mode.



Absolute Maximum Ratings

Absolute Maximum Ratings					
Parameter	Symbol	Rating	Unit		
Supply Voltage	Vcc	0 to + 5.5	V		
Operating Temperature	Topr	-10 to 50	°C		
Storage Temperature	Tstg	-30 to 70	°C		
Operating Humidity (1)	RHopr	0 to 95	%		
Storage Humidity (1)	RHstg	0 to 95	%		

¹⁾ Non-condensing

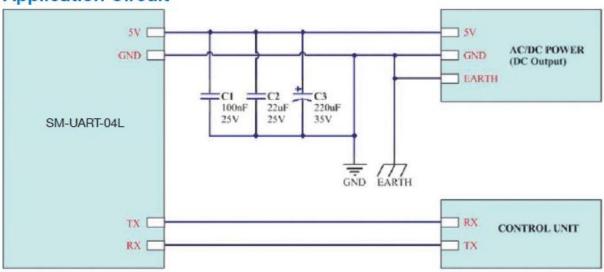
Electrical Characteristics

Parameter		Symbol	Min.	Тур.	Max.	Unit
Particle Size		D	0.3	2.5	10	um
Detection Range		D _{reg}	1	1 - 21	999	μg/m³
Resolution		R	-	1	-	μg /m³
	1 ~100 ug/m ³		-	-	+/-10	μg /m³
Indication Error (2)	100~999 ug/m ³	D _{err}	870	88-88	+/-10	%
Warm-Up Time		t _{wup} (2)	- 2/2	5	<u> </u>	S
Response Time		t _{rsp} (2)	-	1		S
Laser Life (Average Ti	me Before Re-Calibration)	T	- 824	40,000	-	hour
Supply Voltage		V _{oo}	4.8	5	5.2	V
Supply Voltage Ripple		V _∞ Ripple			30	mV
Current Consumption		I ₀₀ (2)		60	100	mA
Output (UART)		3.3V				

¹⁾ Non-condensing

The Telaire SM-UART-04L sensor is used only when needed, a UART transmission put the sensor in sleep mode and wakes it up for a measurement. The typical application connection is shown in the following picture.

Application Circuit



²⁾ Testing at T=25°C, RH=40-60%

2.2 Microcontroller



The choice for the microcontroller unit (MCU) to be used in the project is a fixed requirement; the MCU used is the CC2640R2F from TI. This particular MCU offers both 4.1 and 5.0 Bluetooth connectivity for low energy applications. This particular MCU have a 32-bit ARM Cortex-M3 core, up to 128 Kbytes of flash memory, up to 20 kbytes of SRAM and supports I2C, UART and many more common interfaces. A functional diagram of the MCU is as follows

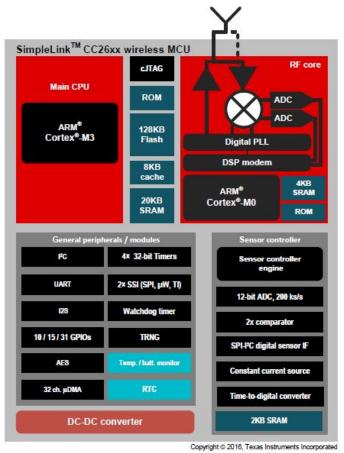


Figure 1-1. Block Diagram

This MCU is available in different packages, my choice was to employ the 7x7 mm VQFN 48 pins RGZ package for ease of use in case of potentially building the circuit at a different time. The electrical characteristics of the MCU are as follows

Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)(2)

		MIN	MAX	UNIT
Supply voltage (VDDS, VDDS2, and VDDS3)	VDDR supplied by Internal DC-DC regulator or Internal GLDO: VDDS_DCDC connected to VDDS on PCB.	-0.3	4.1	ν
Supply voltage (VDDS ⁽³⁾ and VDDR)	External regulator mode (VDDS and VDDR pins connected on PCB)	-0.3	2.25	٧
oltage on any digital pin (4)(5) –0.3 VDDSx + 0.3, max 4.1				٧
Voltage on crystal oscillator pins,	soliator pins, X32K_Q1, X32K_Q2, X24M_N and X24M_P = -0.3 VDDR + 0.3, max 2.25		٧	
	Voltage scaling enabled	-0.3	VDDS	
Voltage on ADC Input (Vin)	Voltage scaling disabled, Internal reference -0.3		1.49	V
	Voltage scaling disabled, VDDS as reference	-0.3	VDDS / 2.9	
Input RF level			5	dBm
T _{stg}	Storage temperature	-40	150	.c

(4) Including analog-capable DIO.
 (5) Each pin is referenced to a specific VDDSx (VDDS, VDDS2 or VDDS3). For a pin-to-VDDS mapping table, see Table 6-3.

5.2 ESD Ratings

				VALUE	UNIT
V _{ESD}	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS001 (1)	All pins	±2500	
	(ESD) performance		RF pins	±750	٧
			Non-RF pins	±750	

JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
 JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Ambient temperature range		-40	85	.c
Operating supply voltage (VDDS and VDDR), external regulator mode	For operation in 1.8-V systems (VDDS and VDDR pins connected on PCB, internal DC- DC cannot be used)	1.7	1.95	ν
Operating supply voltage VDDS	For operation in battery-powered and 3.3-V systems	1.8	3.8	V
Operating supply voltages VDDS2 and VDDS3	nternal DC-DC can be used to minimize power onsumption)	0.7 × VDDS, min 1.8	3.8	٧

All voltage values are with respect to ground, unless otherwise noted.
 Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
 In external regulator mode, VDDS2 and VDDS3 must be at the same potential as VDDS.

5.4 Power Consumption Summary

Measured on the TI CC2650EM-5XD reference design with T_c = 25°C, V_{DDS} = 3.0 V with internal DC-DC converter, unless otherwise noted.

	PARAMETER	TEST CONDITIONS	MIN TYP	MAX	UNIT
		Reset. RESET_N pin asserted or VDDS below Power-on-Reset threshold	100		nA
		Shutdown. No clocks running, no retention	150		6.050
		Standby. With RTC, CPU, RAM and (partial) register retention. RCOSC_LF	1	0.00	
		Standby. With RTC, CPU, RAM and (partial) register retention. XOSC_LF	1.2		
	540 00 00 000	Standby. With Cache, RTC, CPU, RAM and (partial) register retention. RCOSC_LF	2.5		μА
core	Core current consumption	Standby. With Cache, RTC, CPU, RAM and (partial) register retention. XOSC_LF	2.7		
		Idle. Supply Systems and RAM powered.	550		
		Active. Core running CoreMark	1.45 mA + 31 μA/MHz	0.0	
		Radio RX (1)	5.9	- 3	
		Radio RX ⁽²⁾	6.1		
		Radio TX, 0-dBm output power ⁽¹⁾	6.1	- 0	mA.
		Radio TX, 5-dBm output power ⁽²⁾	9.1		
eriph	eral Current Consumption (Ad	dds to core current l _{core} for each peripheral unit ac	tivated) ⁽³⁾		
1115	Peripheral power domain	Delta current with domain enabled	20		μA
	Serial power domain	Delta current with domain enabled	13	- 3	μА
	RF Core	Delta current with power domain enabled, clock enabled, RF core idle	237		μА
	μDMA	Delta current with clock enabled, module idle	130		μA
pert	Timers	Delta current with clock enabled, module idle	113	- 3	μA
	I ² C	Delta current with clock enabled, module idle	12		μА
	125	Delta current with clock enabled, module idle	36		μA
	SSI	Delta current with clock enabled, module idle	93		μA
	UART	Delta current with clock enabled, module idle	164		μA

- Single-ended RF mode is optimized for size and power consumption. Measured on CC2650EM-4XS. Differential RF mode is optimized for RF performance. Measured on CC2650EM-5XD. $I_{\rm perf}$ is not supported in Standby or Shutdown.

2.3 Power block

2.3.1 Rechargeable battery



The Mikroelektronika HPL402323-2C-190mAh battery is a small footprint Li-Po battery. With a capacity of 190 mAh and a possibility of discharging a continuous current of 380 mA it is a suitable battery to deliver the 100 mA max. peak current to the PM2.5 sensor. It is charged at 4.2 V and is 3 V when completely discharged. The battery includes protection circuitry to protect the battery from over charge and over discharge. The main specifications are as follows

4.Product Specification

4.1 Specification Table 1

No.	Item	Rated Perform	mance	Remark		
	Dated Councils	Typical	190mAh	Discharge at 0.2C ₅ A after standard		
1	Rated Capacity	Minimum	190mAh	charge fully.		
2	Nominal Voltage	3.7V		Mean operation voltage during standard discharge.		
3	Voltage at end of Discharge	3.0V		Discharge cut-off voltage.		
4	Charging Voltage	4.2±0.03V				
5	AC (1KHz) Impedance New Cell Max.(mΩ)	≤250mΩ				
6	Standard Charge	Constant Current 0.5CsA Constant Voltage 4.2V 0.01 CsA cut-off		Charge time: Approx 4.0h.		
7	Standard Discharge	Constant current 0.2 CsA end voltage 3.0V		Discharge time: Approx 6.0h.		
8	Fast Charge	Constant Current 1C ₂ A Constant Voltage 4.2V 0.01 C ₄ A cut-off		Charge time: Approx 2.5h.		
9	Fast Discharge	Constant current 2C ₅ A end voltage 3.0V				
10	Maximum Continuous Charge Current	1.0C ₅ A				
11	Maximum Continuous Discharge Current	2.0C ₅ A				
12	Operation Temperature	Charge: 0~45	rc ·	- Control		
12	Range	Discharge: -2	0~60°C	- 60±25%RH.		
		Less than 1 y	ear: -20~25°C			
13	Storage Temperature Range	Less than 3 m	nonths: -20~40°C	60±25%RH.		
	Range	1 Week: -20~	60°C	40% 0 % 5 % 5 % 5 % 5 % 5 % 5 % 5 % 5 % 5		
14	Storage Humidity Range	60±25%RH.				
15	Weight	Approx: 4.5 g	00	Whole product		
		Thickness: Max. 4.2mm Width: Max.23.5mm Length:Max.24.5mm				
16	Product Dimension			Initial dimension		
	Section of the sectio					

2.3.2 Battery charger



The MAX1555 by MAXIM charges a single-cell lithium-ion (Li+) battery from both USB and AC adapter sources. My choice was to employ a micro-usb connector and exploit the USB capabilities of the MAX1555. The main specifications for the battery charger are as follows

ELECTRICAL CHARACTERISTICS

(VDC = 5V, VUSB = 0, IBAT = 0, CBAT = 1µF, TA = 0°C to +85°C, unless otherwise noted.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
DC	-111 1041115 211				
DC Voltage Range	(Note 1)	3.7		7.0	V
DC to BAT Voltage Range		0.1		6.0	٧
DC Undervoltage Lockout Threshold	Input rising, 430mV hysteresis, V _{BAT} = 3V (Note 1)	3.75	3.95	4.15	٧
DC Supply Current			1.75	3	mA
DC to BAT On-Resistance	VDC = 3.7V, VBAT = 3.6V		13	2	Ω
DC to BAT Dropout Voltage	When charging stops, V _{BAT} = 4V, DC falling, 200mV hysteresis	30	60	90	mV
USB		*		100	
USB Voltage Range	(Note 1)	3.7		6.0	V
USB Undervoltage Threshold	Input rising, 430mV hysteresis, V _{DC} = 0, V _{BAT} = 3V (Note 1)	3.75	3.95	4.15	٧
USB Supply Current	Vus8 = 5V, Vpc = 0	18	1.65	3	mA
USB to BAT On-Resistance	VusB = 3.7V, VBAT = 3.6V, VDC = 0		2	4	Ω
USB to BAT Dropout Voltage	When charging stops, V _{BAT} = 4V, USB falling, 200mV hysteresis, V _{DC} = 0	30	60	90	mV
BAT		**		**	
BAT Regulation Voltage	V _{DC} or V _{USB} = 5V	4.158	4.2	4.242	V
DC Charging Current	VBAT = 3.3V, VuSB = 0, VDC = 5V	220	280	340	mA
USB Charging Current	VBAT = 3.3V, VDC = 0, VUSB = 5V	80	90	100	mA
BAT Prequal Threshold	VBAT rising, 100mV hysteresis	2.9	3	3.1	V
Prequalification Charging Current	$V_{BAT} = 2.8V$	20	40	80	mA
BAT Leakage Current	V _{DC} = V _{USB} = 0, V _{BAT} = 4.2V			5	μА
POK, CHG, AND THERMAL LIMIT		59			8
CHG Threshold	Charge current where CHG goes high, IBAT falling, 50mA hysteresis	25	50	100	mA
CHG, POK Logic-Low Output	ICHG, IPOK = 10mA	3	150	300	mV
CHG, POK Leakage Current	VCHG, VPOK = 6V, TA = +25°C		0.001	1	μА
Thermal-Limit Temperature	Charge current reduced by 17mA/°C above this temperature		+110		°C

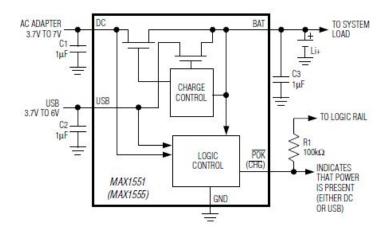
ELECTRICAL CHARACTERISTICS

(VDC = 5V, VUSB = 0, IBAT = 0, CBAT = 1µF, TA = -40°C to +85°C, unless otherwise noted.) (Note 2)

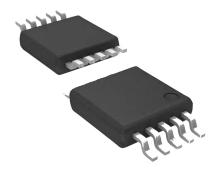
PARAMETER	CONDITIONS	MIN	MAX	UNITS
DC	40000	72.		
DC Voltage Range	(Note 1)	3.7	7.0	V
DC to BAT Voltage Range		0.1	6.0	V
DC Undervoltage Lockout Threshold	Input rising, 430mV hysteresis, V _{BAT} = 3V (Note 1)	3.75	4.15	V
DC Supply Current		7	3	mA
DC to BAT On-Resistance	VDC = 3.7V, VBAT = 3.6V		2	Ω
DC to BAT Dropout Voltage	When charging stops, V _{BAT} = 4V, DC falling, 200mV hysteresis	30	95	mV
USB	1	•		
USB Voltage Range	(Note 1)	3.7	6.0	V
USB Undervoltage Lockout Threshold	Input rising, 430mV hysteresis, V _{DC} = 0, V _{BAT} = 3V (Note 1)	3.75	4.15	V
USB Supply Current	VusB = 5V, VDC = 0		3	mA
USB to BAT On-Resistance	Vusa = 3.7V, Vaat = 3.6V, VDC = 0		4	Ω
USB to BAT Dropout Voltage	When charging stops, V _{BAT} = 4V, USB falling, 200mV hysteresis, V _{DC} = 0	30	95	mV
BAT	*	15		2 0
BAT Regulation Voltage	V _{DC} or V _{USB} = 5V	4.141	4.259	V
DC Charging Current	VBAT = 3.3V, VUSB = 0, VDC = 5V	220	340	mA
USB Charging Current	VBAT = 3.3V, VDC = 0, VUSB = 5V	80	100	mA
BAT Prequal Threshold	VBAT rising, 100mV hysteresis	2.9	3.1	V
Prequalification Charging Current	$V_{BAT} = 2.8V$	20	80	mA
BAT Leakage Current	VDC = VUSB = 0, VBAT = 4.2V	76	5	μА
POK, CHG	8	00		
CHG Threshold	Charge current where CHG goes high, IBAT falling, 50mA hysteresis	25	100	mA
CHG, POK Logic-Low Output	ICHG, IPOK = 10mA		300	mV
CHG, POK Leakage Current	VCHG, VPOK = 6V, TA = +25°C	1	1	μА

PIN	NAME	FUNCTION
1	USB	USB Port Charger Supply Input. USB draws up to 100mA to charge the battery. Decouple USB with a 1µF ceramic capacitor to GND.
2	GND	Ground
	POK	Power-OK Active-Low Open-Drain Charger Status Indicator. POK pulls low when either charger source is present (MAX1551 only).
3	CHG	Active-Low Open-Drain Charge Status Indicator. CHG pulls low when the battery is charging. CHG goes to a high-impedance state, indicating the battery is fully charged, when the charger is in voltage mode and charge current falls below 50mA. CHG is high impedance when both input sources are low (MAX1555 only).
4	DC	DC Charger Supply Input for an AC Adapter. DC draws 280mA to charge the battery. Decouple DC with a 1µF ceramic capacitor to GND.
5	BAT	Battery Connection. Decouple BAT with a 1µF ceramic capacitor to GND.

The MAX1555 does not have an enable pin, so as soon as power is connected the battery is charged. A typical application circuit, which can be found in the datasheet, is as follows



2.3.3 Voltage regulator



The MAX1759 by MAXIM is a buck/boost regulating charge pump that generates a regulated output voltage from a single lithium-ion (Li+) cell. The main features for the voltage regulator are as follows

ELECTRICAL CHARACTERISTICS

(Circuit of Figure 1, $V_{IN} = V_{\overline{SHDN}} = 2V$, FB = PGND = GND, $C_{IN} = 10\mu\text{F}$, $C_X = 0.33\mu\text{F}$, $C_{OUT} = 10\mu\text{F}$, $T_A = 0^{\circ}\text{C}$ to +85°C, unless otherwise noted. Typical values are at $T_A = +25^{\circ}\text{C}$.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT	
Input Voltage Range	VIN	1	1.6		5.5	٧	
Input Undervoltage Lockout Voltage	Vuvlo		0.6	1.0	1.4	V	
Output Voltage Adjustment Range		1.6V ≤ V _{IN} ≤ 5.5V	2.5		5.5	V	
Outra d Voltage	V _{OUT}	$2V \le V_{IN} \le 5.5V$, $1mA \le I_{LOAD} \le 50mA$	3.17	3.3	3.43	V	
Output Voltage		$2.5V \le V_{IN} \le 5.5V$, $1mA \le I_{LOAD} \le 100mA$	3.17	3.3	3.43		
Maximum Output Current	LOAD,MAX	$2.5V \le V_{IN} \le 5.5V$	100			mA	
Transient Load Current		ILOAD ≤ 100mA (RMS)		200		mA	
Outland and Committee Committee	le.	V _{IN} = V SHDN = 4V, V _{FB} = 0, stepping down		50	90	μА	
Quiescent Supply Current	lo:	V _{IN} = V SHDN = 2V, V _{FB} = 0, stepping up		85	180		
Shutdown Supply Current	utdown Supply Current IQ,SHDN 1.6V ≤ VIN ≤ 5.5V, V SHDN = 0		=	1	5	μА	
Leakage Current into OUT in Shutdown		$V_{IN} = 2V$, $V_{OUT} = 3.3V$, $V \overrightarrow{SHDN} = 0$		1	5	μА	
ollow	VIL	1.6V ≤ V _{IN} ≤ 5.5V	0.25 · V _{IN}		V		
SHDN Logic Input Voltage	VIH	1.6V ≤ V _{IN} ≤ 5.5V	0.7 · VIN			1 *	
SHDN Input Leakage Current	ISHDN	V SHON = 5.5V	-1		1	μА	
FB Regulation Voltage	VFB	V _{IN} = 1.65V, V _{OUT} = 3.3V	1.205	1.235	1.265	V	
FB Input Current		V _{FB} = 1.27V		25	200	nΑ	
FB Dual-Mode Threshold		Internal feedback		100	50	mV	
FB Dual-Mode Threshold		External feedback	200	100		mV	
POK Trip Voltage		Falling edge at FB	1.0	1.1	1.2	٧	
POK Output Low Voltage	Vol	Isink = 0.5mA, Vin = 2V	9	5	100	mV	
POK Leakage Current		$V_{POK} = 5.5V$, $V_{FB} = 1.27V$		0.01	0.2	μА	
Switching Frequency	fosc	$1.6V \le V_{IN} \le 5.5V$, $V_{FB} = 1V$	1.2	1.5	1.8	MHz	
Output Short-Circuit Current		$V_{OUT} = 0$, $2.5V \le V_{IN} \le 5.5V$, foldback current limit	it 110		mA		
Thermal Shutdown Temperature		Rising temperature		160		"C	
Thermal Shutdown Hysteresis			8	20	- 8	°C	
Efficiency		V _{IN} = 3.6V, I _{LOAD} = 10mA		90		%	

ELECTRICAL CHARACTERISTICS

(Circuit of Figure 1, $V_{IN} = V_{\overline{SHDN}} = 2V$, FB = PGND = GND, $C_{IN} = 10\mu$ F, $C_{X} = 0.33\mu$ F, $C_{OUT} = 10\mu$ F, T_{A} = -40°C to +85°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS
Input Voltage Range	VIN		1.6	5.5	V
Input Undervoltage Lockout Voltage	V _{UVLO}		0.6	1.4	٧
Outer d Veltage	Vout	$2V \le V_{IN} \le 5.5V$, $0 \le I_{LOAD} \le 50$ mA	3.15	3.45	V
Output Voltage		$2.5V \le V_{IN} \le 5.5V$, $0 \le I_{LOAD} \le 100mA$	3.15	3.45	V
Output Voltage Adjustment Range		1.6V ≤ V _{IN} ≤ 5.5V	2.5	5.5	٧
Maximum Output Current	LOAD,MAX	$2.5V \le V_{IN} \le 5.5V$	100		mA
0.:101	la	VIN = V SHON = 4V, VFB = 0	400	90	
Quiescent Supply Current		$V_{IN} = V_{SHDN} = 2.5V, V_{FB} = 0$	100	180	μА
Shutdown Supply Current	IQ,SHDN	$1.6V \le V_{IN} \le 5.5V$, $V \overrightarrow{SHDN} = 0$	87	6	μA
Leakage Current into OUT in Shutdown		V _{IN} = 2V, V _{OUT} = 3.3V, V SHDN = 0		5	μА
alleri i i i i	VIL	1.6V ≤ V _{IN} ≤ 5.5V	43	0.2 · VIN	V
SHDN Input Logic Voltage	VIH	1.6V ≤ V _{IN} ≤ 5.5V	0.7 • VIN	111	V
SHDN Input Leakage Current	ISHON	V SHON = 5.5V	-1	1	μА
FB Regulation Voltage	V _{FB}	V _{IN} = 1.65V, V _{OUT} = 3.3V	1.205	1.265	V
FB Input Bias Current	0 0	V _{FB} = 1.27V	8	200	пA
FB Dual Mode Threshold		Internal feedback	62 11111	40	mV
PB Dual Mode Threshold		External feedback	200		mV
POK Trip Voltage		Falling edge at FB	1.0	1.2	V
POK Output Low Voltage	VOL	$I_{SINK} = 0.5mA$, $V_{IN} = 2V$	87	100	mV
POK Leakage Current	-1 -07 -04	V _{POK} = 5.5V	22 22 - 7070	0.2	μА
Switching Frequency	fosc	$1.6V \le V_{IN} \le 5.5V$, $V_{FB} = 1V$	1.1	1.9	MHz

A typical application circuit for step-up, step-down and 3.3V output functionalities are as follows

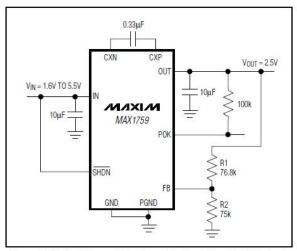


Figure 3. Using External Feedback for Regulated 2.5V Output

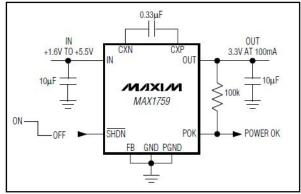


Figure 1. Typical Application Circuit

2.4 Switch



The JS202011SCQN-DPDT switch has been used. The switch is used to cut off the Li-Po battery from the circuit. The main specifications for the JS202011SCQN-DPDT switch are as follows

Specifications

CONTACT RATING: 6 VDC @ 0.3A

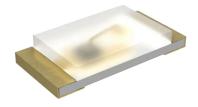
ELECTRICAL LIFE: 5,000 make-and-break cycles

CONTACT RESISTANCE: 70 m Ω max.

INSULATION RESISTANCE: 100 M Ω min. @ 500V. DIELECTRIC STRENGTH: 500 VAC min. @ sea level.

OPERATING TEMPERATURE: -40°C to +85°C STORAGE TEMPERATURE: -40°C to +85°C

2.5 LED



The APG1608ZGC from Kingbright LED's are used for the design. Typical applications for this component are status indicator, backlight and wearable and portable devices as stated in the datasheet. The main characteristics for this component are as follows

FEATURES

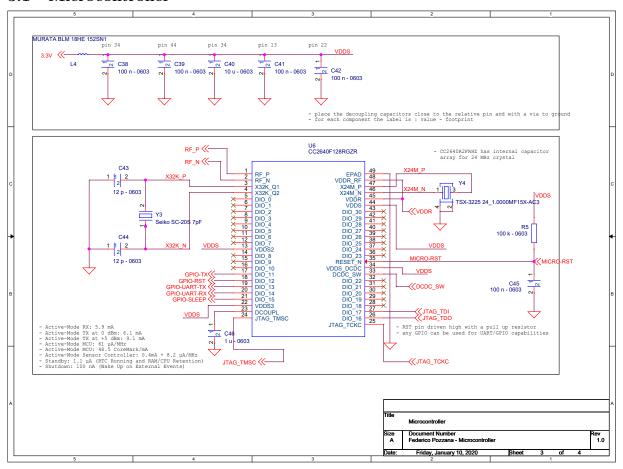
- 1.6 mm x 0.8 mm SMD LED, 0.25 mm thickness
- Low power consumption
- Wide viewing angle
- · Compatible with automatic placement equipment
- · Ideal for backlight and indicator
- · Package: 4000 pcs / reel
- · Moisture sensitivity level: 3
- RoHS compliant

3 Schematics

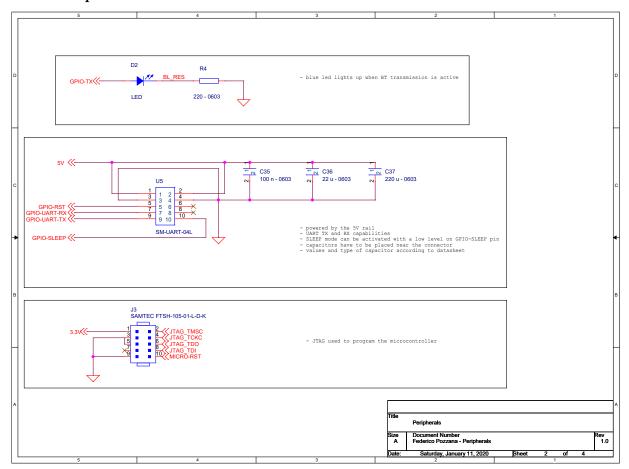
The schematics for this project are designed using ORCAD Capture. It is possible to identify four possible sections for the PAR.MA. project

- ullet Microcontroller
- \bullet Peripherals
- \bullet Power
- \bullet RF

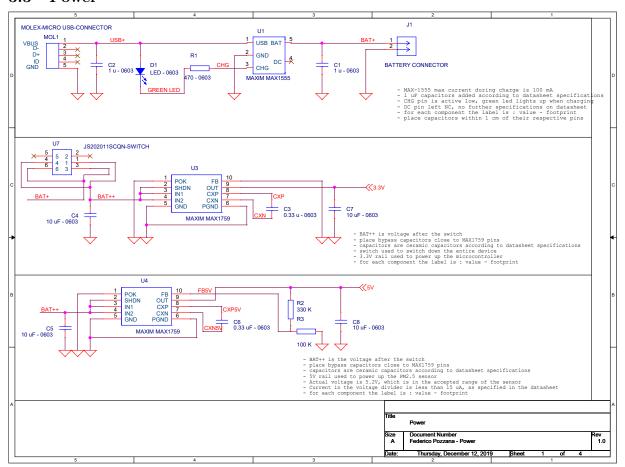
3.1 Microcontroller



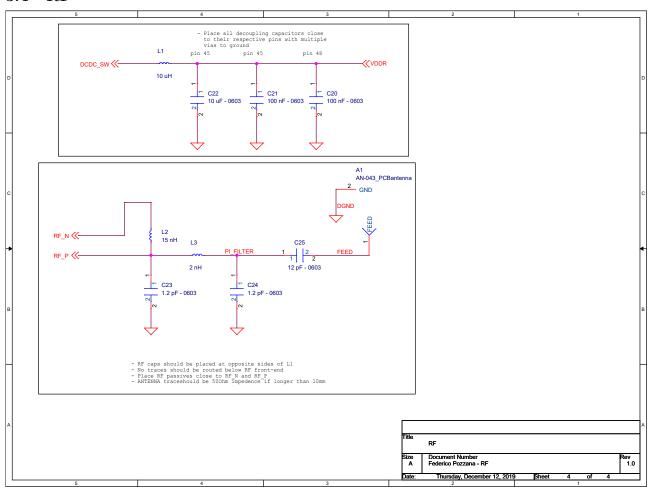
3.2 Peripherals



3.3 Power



3.4 RF



3.5 Bill of materials

The output below reports the bill of material extracted from the schematic.

Bill Of Materials			January 10,2020		17:37:56	Page1
Item	Quant	ity	Reference	Part		
1	1	A1	AN-043 PCBant	enna		
2	3	C27,C2	3,C46 1 u -	0603		
3	6	C29, C3	0,C33,C34,C40,C	50 10 u	- 0603	
4	2	C31,C3	2 0.33 u - 0603			
5	8	CONTROL (1997)	3, C39, C41, C42, C		52 100 n -	0603
6	1	C36	22 u - 0603	18 18		
7	1	C37	220 u - 0603			
8	3	C43,C4	1,C49 12 p	- 0603		
9	2		3 1.2 p - 0603			
10	1	D1	LED - 0603			
11	1	D2	LED			
12	1	J1	BATTERY CONNE	CTOR		
13	1	J3	SAMTEC FTSH-1	05-01-L-	D-K	
14	1	L1	10 uH			
15	1	L2	15 nH			
16	1	L3	2 nH			
17	1	L4	MURATA BLM 18	HE 152SN	1	
18	1	MOL1	MOLEX-MICRO U	SB-CONNE	CTOR	
19	1	R1	470 - 0603			
20	1	R2	330 K			
21	1	R3	100 K			
22	1	R4	220 - 0603			
23	1	R5	100 k - 0603			
24	2	U3,U4	MAXIM MAX1759			
25	1	U5	SM-UART-04L			
26	1	U6	CC2640F128RGZ	R		
27	1	U8	MAXIM MAX1555			
28	1	U9	JS202011SCQN-	DPDT-SWI	TCH	
29	1	Y3	Seiko SC-20S			
30	1	Y4	TSX-3225 24 1		5X-AC3	

4 Allegro

The top and bottom layer of the PCB are reported in the PCBPROTO.pdf file.

The ground plane is absent below the antenna in order to avoid interferences during transmission and reception in that particular direction. All the decoupling and bypass capacitors were placed as close as possible to the respective pins. The bottom layer is reserved to the ground plane and some traces that couldn't be routed in the top layer.

5 Conclusion

The project is ready to be manufactured, however the goal for this project is to deliver the gerber files without building it. For this reason no app and firmware are going to be developed.